

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT4673282

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIH-HORNG CHANG	10/07/2014
TIN-HAO KUO	10/07/2014
CHEN-SHIEN CHEN	10/07/2014
YEN-LIANG LIN	10/07/2014
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	HSIN-CHU SCIENCE PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15803008
CORRESPONDENCE DATA	
Fax Number:	(216)502-0601
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	216-502-0600
Email:	docketing@eschweilerlaw.com
Correspondent Name:	ESCHWEILER & POTASHNIK, LLC
Address Line 1:	ROSETTA CENTER
Address Line 2:	629 EUCLID AVE., SUITE 1000
Address Line 4:	CLEVELAND, OHIO 44114
ATTORNEY DOCKET NUMBER:	TSMCP662USC
NAME OF SUBMITTER:	JAMES R. POTASHNIK
SIGNATURE:	/James R. Potashnik/
DATE SIGNED:	11/03/2017
Total Attachments: 1	

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- 1) Chih-Hong CHANG
- 2) Tin-Hao KUO
- 3) Chen-Shien CHEN
- 4) Yen-Liang LIN

who has made a certain new and useful invention, hereby sells, assigns and transfers unto TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD., having a place of business at No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan R.O.C.

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

BUMP STRUCTURE HAVING A SINGLE SIDE RECESS

(a) for which an application for United States Letters Patent was filed on 2014-10-06, and identified by United States Patent Application No. 14/507,189; or

(b) for which an application for United States Letters Patent was executed on _____

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) Chih-Hong Chang
Name: Chih-Hong CHANG

7. Oct. 2014
Date:

2) Tin-Hao KUO
Name: Tin-Hao KUO

7. Oct. 2014
Date:

3) Chen Shien Chen
Name: Chen-Shien CHEN

7. Oct. 2014
Date:

4) Yen-Liang Lin
Name: Yen-Liang LIN

7. Oct. 2014
Date: